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**PATENT**  
Attorney Docket No. 402715

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

KUMADA et al.

Application No. 10/623,772

Art Unit: 2812

Examiner: L. Schillinger

Filed: July 22, 2003

For: VIA-FILLING MATERIAL AND  
PROCESS FOR FABRICATING  
SEMICONDUCTOR INTEGRATED  
CIRCUIT USING THE SAME

**RESPONSE TO OFFICE ACTION**

U.S. Patent and Trademark Office  
220 20<sup>th</sup> Street S. Customer Window, Mail Stop Amendment  
Crystal Plaza Two, Lobby, Room 1B03  
Arlington, VA 22202

Dear Sir:

In response to the Office Action dated November 23, 2004, please enter the following amendments and consider the following remarks.

- In re Appln. of KUMADA et al.  
Application No. 10/623,772

*TITLE AMENDMENTS*

**~~VIA-FILLING MATERIAL AND PROCESS FOR FABRICATING  
SEMICONDUCTOR INTEGRATED CIRCUIT USING THE SAME~~**